



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C151JB8NNWC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 150pF, 50V, ±5%, C0G, 0603

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>151</u> <u>J</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>W</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor			
2	Size	0603 (inch code)	L: 1.6 ± 0.1 mm	W: 0.8 ± 0.1	mm
3	Dielectric	C0G	8 Inner electrode	Ni	
4	Capacitance	150 pF	Termination	Cu	
⑤	Capacitance	±5 %	Plating	Sn 100%	(Pb Free)
	tolerance		Product	Normal	
6	Rated Voltage	50 V	Special	Product for N	letwork application
7	Thickness	0.8 ± 0.1 mm	① Packaging	Cardboard T	ype, 7" reel

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition		
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms		
Q	1000 min			
Insulation	10,000Mohm or 500Mohm⋅μF	Rated Voltage 60~120 sec.		
Resistance	Whichever is Smaller			
Appearance	No abnormal exterior appearance	Microscope (×10)		
Withstanding	No dielectric breakdown or	300% of the rated voltage		
Voltage	mechanical breakdown			
Temperature C0G				
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)			
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.		
of Termination	terminal electrode			
Bending Strength	Capacitance change :	Bending to the limit (1mm)		
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.		
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder		
	is to be soldered newly	245±5℃, 3±0.3sec.		
		(preheating : 80~120 ℃ for 10~30sec.)		
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.		
Soldering heat	within ±2.5% or ±0.25pF whichever is larger			
	Tan δ, IR : initial spec.			

	Performance	Test condition	
Vibration Test	Capacitance change :	Amplitude : 1.5mm	
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)	
	Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)	
Moisture	Capacitance change :	With rated voltage	
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs	
	Q: 200 min		
	IR: 500Mohm or 25Mohm $\cdot \mu$ F		
	Whichever is Smaller		
High Temperature	Capacitance change :	With 200% of the rated voltage	
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature	
	Q: 350 min	1000+48/-0hrs	
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F		
	Whichever is Smaller		
Temperature	Capacitance change :	1 cycle condition	
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperature → 25 °C	
	Tan δ, IR : initial spec.	→ Max. operating temperature → 25°C	
		5 cycle test	

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C , 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.